

Tendencias e Innovación en Printed Electronics para sector Ferroviario

Functional Printing & Embedded Devices Unit

"innovating for business"



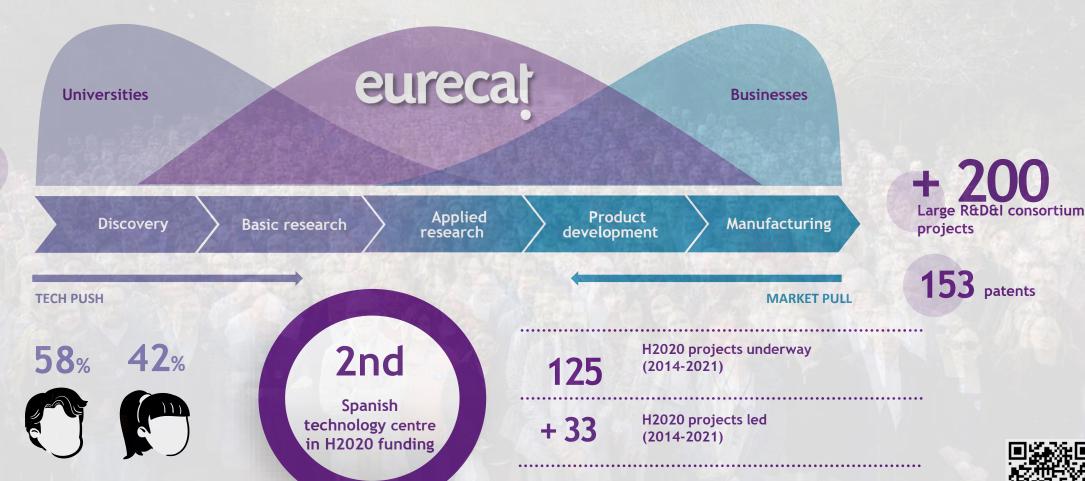
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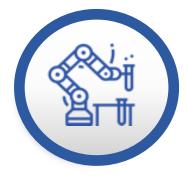
staff

BRIDGE FROM BASIC RESEARCH TO MARKET

Quite a challenge ... which opens up great opportunities



Our interdisciplinary capabilities enable us to address complex challenges.



Industrial Area

- 1. Advanced materials and new manufacturing processes
- 2. Functional Printing & Embedded Devices
- 3. Collaborative and cognitive robotics
- 4. Functional textiles
- 5. Chemicals
- 6. Modelling and simulation
- 7. Product development



Digital **Area**

- 1. Sensor systems and IoT
- 2. Data science and analytics
- 3. Artificial intelligence
- 4. Cybersecurity
- 5. Multimedia technologies
- 6. Digital Health



Biotechnology Area

- 1. Nutrition and health
- 2. Omic sciences
- 3. Biotechnology



Sustainability Area

- 1. Water
- 2. Soil
- 3. Air
- 4. Energy
- 5. Waste
- 6. Environmental impact
- 7. Batteries
- 8. Climate change

An interdisciplinary group focused on thin-film printed, flexible and hybrid devices embedded into smart surfaces and objects.



Printed Health & **Environmental Sensors**

monitoring



Design and development of ad hoc printed devices harvesting, generation & health and environmental conversion with emphasis in green hydrogen technologies



In Mould Electronics

Design and manufacturing of functional and decorative films for plastic, composites, silicone and elastomers devices integration.



Smart Engineering

Design and development of embedded systems and IoT devices to fulfill any need in the industry, smart cities or health/medical environment.



Projects in execution



Labs. From research to industrial preseries

Labs Virtual Tour







Printed Electronics

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Printed electronics enables the production of flexible and large-area components and complements silicon electronics.





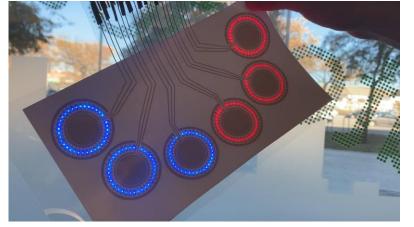




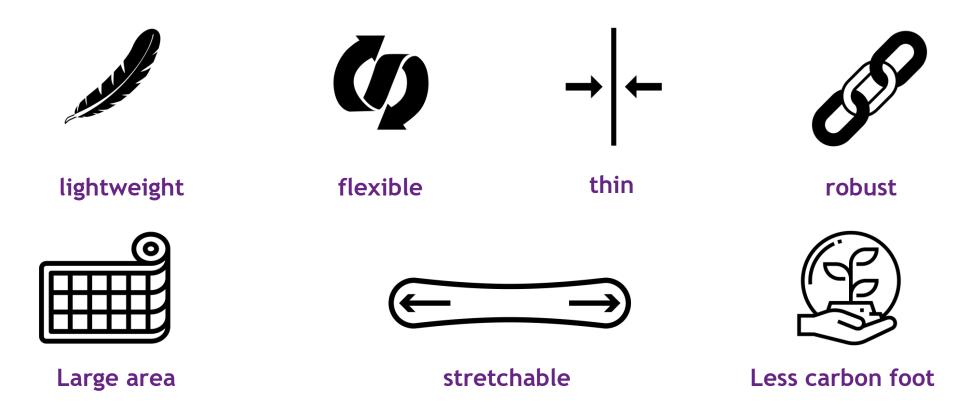








Printed electronics enables the production of flexible and large-area components and complements silicon electronics.

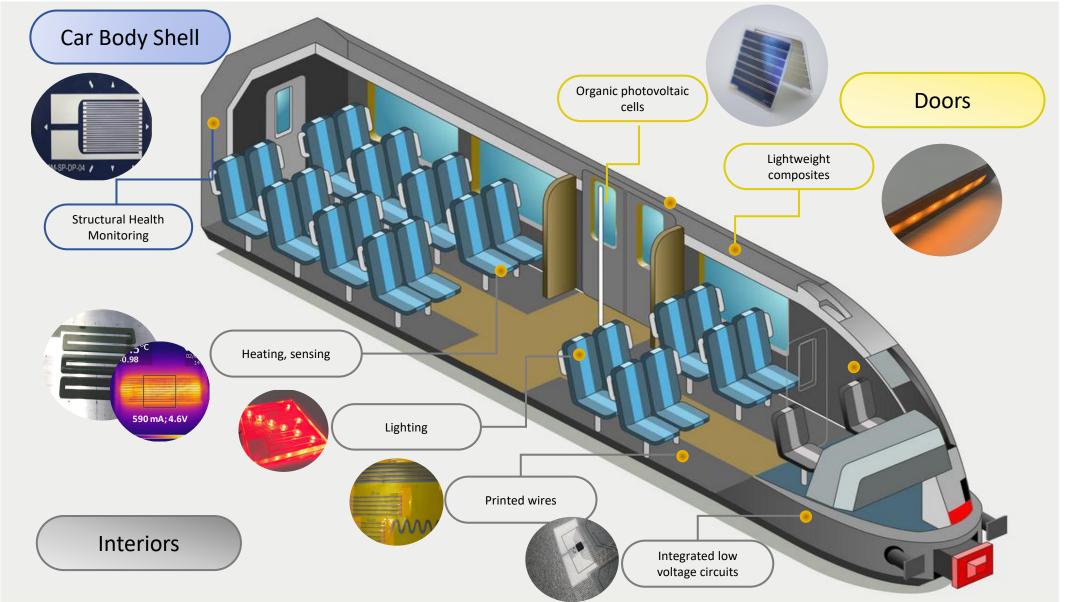


These **key features distinguish** organic and printed electronics from traditional semiconductor technologies.



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RAIL - Opportunities for flexible electronics



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CARBODIN - Car body shells, doors and interiors

The CARBODIN project, coordinated by Eurecat, has the objective to contribute to the next generation of passenger trains that will be lighter and more energy and cost efficient than the current ones.





Eurecat participates in design of molds, modular floor development and printed wires integration for low voltage circuits inside composite panels.





Programme and call for tender

Project funded by the European Union's programme Horizon 2020 within the Shift2Rail (S2R) initiative, H2020-JTI-Shift2Rail-2019, and more specifically under the call S2R-OC-IP1-01-2019: Advanced car Body shells for railways and light material and innovative doors

Project website

www.carbodin.eu



Printed cables to replace part of the interior wiring of trains







S2R-OC-IP1-01-2019/881814

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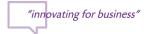
Project website

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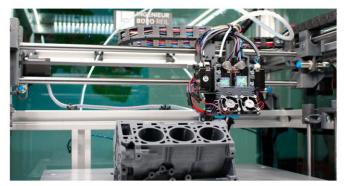


European Commission

Structural Health Monitoring



Strain gauges printed on foils 2D or in 3D shapes for structural health monitoring



The objective of **3DELECPRINT** is to develop an integrated flexible robotic platform to print electronic sensors and/or cables on geometric complex rigid parts in 3D.

The resulting parts are made of different materials, including metal, composites, and ceramic.

The printing system to be used for the project is based on a spray head for ultrasound. This is a versatile technique enabling the use of a wide variety of dyes, with perfect adaptation to the shape of the substrate and a more efficient use of resources given that it under unit have the undergraded to the substrate and the properties of the substrate and the properties of the substrate and the properties of the substrate and the substrate a





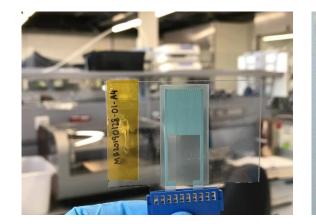
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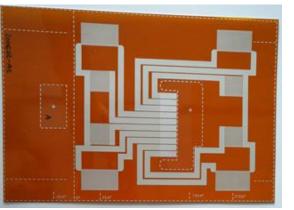


Printed strain gauges on 3D surfaces



https://eurecat.org/en/portfolio-items/flexirapidman/





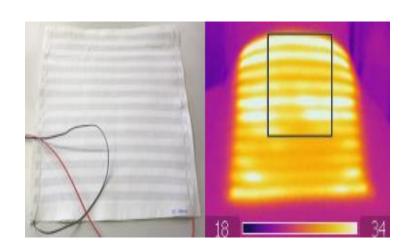
From a single gauge To a sophisticated design to compensate for the effect of temperature

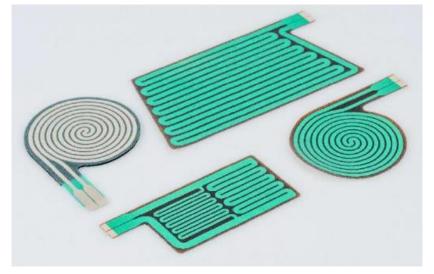


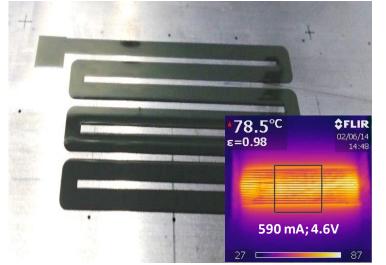
Heating

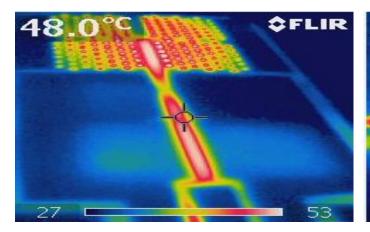


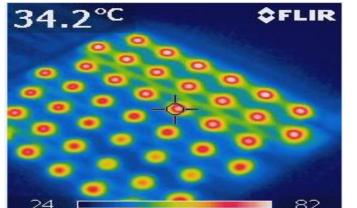
Flexible self-regulating printed heaters to integrate into furniture







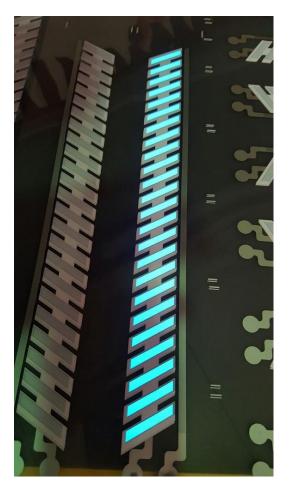


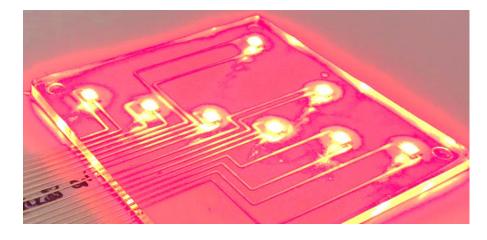




Printed & Embedded Light

Printed & integrated light in plastic, textile & composites









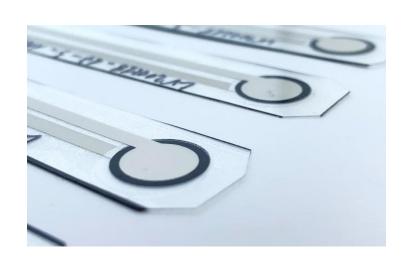
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Smart Touchless Sensors

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Non-contact capacitive sensors for indoor use in the railway sector





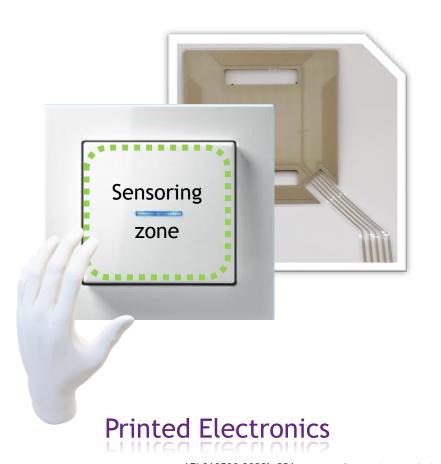




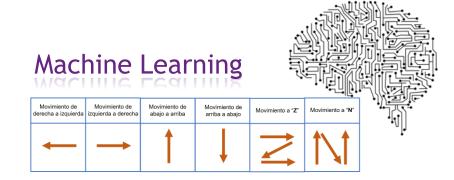
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Smart Touchless Sensors with embedded AI

Gesture recognition with embedded Artificial Intelligence algorithms with digital output in switches to adapt them to the new needs detected in the market (non-contact-high influx of people)









Domotics

AEI-010500-2022b-331: Proyecto financiado a través de la convocatoria "Agrupaciones Empresariales Innovadoras 2022" de la Agencia Estatal de Investigación (Ministerio de Industria, Comercio y Turismo) y la Unión Europea NextGenerationEU / PRTR



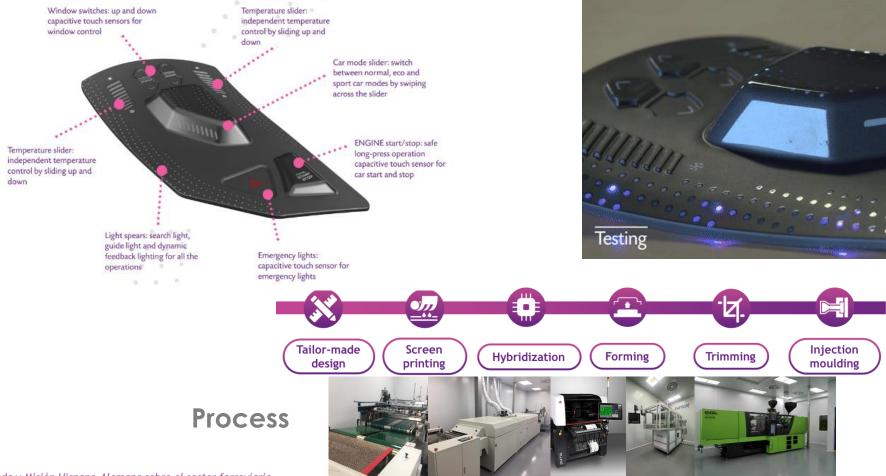






Púlsar - Smart Human Machine Interfaces

Púlsar demonstrates the application of In Mold Electronics in a vehicle centre console. Only 3mm thickness, this smart plastic surface presents an intuitive Humane Machine Interface (HMI) with seamless LED illumination and capacitive sensors, embedded in a monolithical device.





Best Demo Public Award

2024



https://youtu.be/6NpnFmZgl_Y



Functional Printing & Embedded Devices unit Partners



Clusters, associations, and Hubs





















Thank you!







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